(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
02 October 2025 (02.10.2025)

WIPO | PCT

(10) International Publication Number
WO 2025/207735 A1

(51) International Patent Classification:
C23C 16/509 (2006.01) *C23C 16/455* (2006.01)
C23C 16/458 (2006.01) *H01L 21/67* (2006.01)

(21) International Application Number:
PCT/US2025/021491

(22) International Filing Date:
26 March 2025 (26.03.2025)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
18/620,411 28 March 2024 (28.03.2024) US

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(81) Designated States *(unless otherwise indicated, for every kind of national protection available)*: AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CV, CZ, DE, DJ, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IQ, IR, IS, IT, JM, JO, JP, KE, KG, KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY, MA, MD, MG, MK, MN, MU, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH,

(54) Title: GROUNDING PLATE FOR STRESS TUNING HIGH DENSITY AND MODULUS FILMS

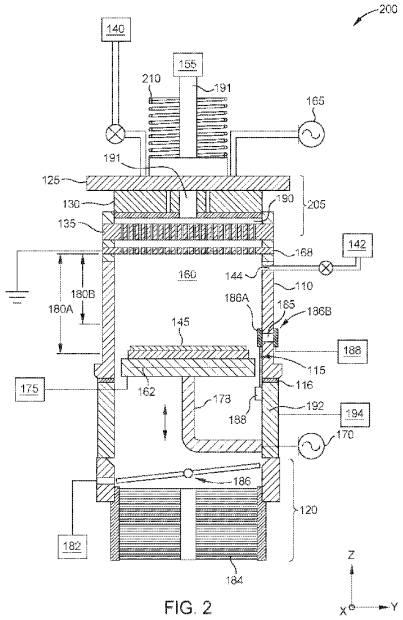


FIG. 2

(57) Abstract: A process chamber for forming film high density and modulus films is provided. The process chamber includes a lid assembly, an inductively coupled plasma source disposed on the lid assembly, and a chamber body coupled to the lid assembly, wherein the lid assembly comprises a non-conductive material for providing a dielectric break between the inductively coupled plasma source and the chamber body. The process chamber also includes a substrate support comprising a powered electrode and a grounding plate coupled to an electrical ground and disposed between the lid assembly and the chamber body. The grounding plate is configured to operate as part of a grounded electrode for generating a plasma in the processing volume between the powered electrode and the grounded electrode.

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[Continued on next page]

TJ, TM, TN, TR, TT, TZ, UA, UG, US, UY, UZ, VC, VN, WS, ZA, ZM, ZW.

(84) **Designated States** *(unless otherwise indicated, for every kind of regional protection available)*: ARIPO (BW, CV, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SC, SD, SL, ST, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, ME, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG).

Published:

— *with international search report (Art. 21(3))*